



## High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, DH

VSMB2000X01



21725-4

VSMB2020X01



### FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- Peak wavelength:  $\lambda_p = 940$  nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity:  $\phi = \pm 12^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reserve gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



### DESCRIPTION

VSMB2000X01 series are infrared, 940 nm emitting diodes in GaAlAs (DH) technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

### APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Control and drive circuits
- Shaft encoders

### Note

\*\* Please see document "Vishay Material Category Policy": [www.vishay.com/doc?99902](http://www.vishay.com/doc?99902)

PRODUCT SUMMARY				
COMPONENT	I <sub>e</sub> (mW/sr)	φ (deg)	λ <sub>p</sub> (nm)	t <sub>r</sub> (ns)
VSMB2000X01	40	± 12	940	15
VSMB2020X01	40	± 12	940	15

### Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMB2000X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMB2020X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

### Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V <sub>R</sub>	5	V
Forward current		I <sub>F</sub>	100	mA
Peak forward current	t <sub>p</sub> /T = 0.5, t <sub>p</sub> = 100 μs	I <sub>FM</sub>	200	mA
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1	A
Power dissipation		P <sub>V</sub>	160	mW
Junction temperature		T <sub>j</sub>	100	°C
Operating temperature range		T <sub>amb</sub>	- 40 to + 85	°C
Storage temperature range		T <sub>stg</sub>	- 40 to + 100	°C
Soldering temperature	t ≤ 5 s	T <sub>sd</sub>	260	°C
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R <sub>thJA</sub>	250	K/W

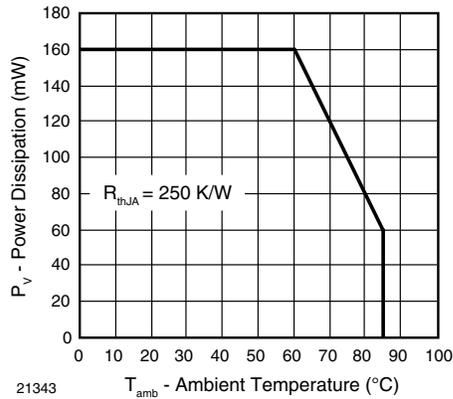


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

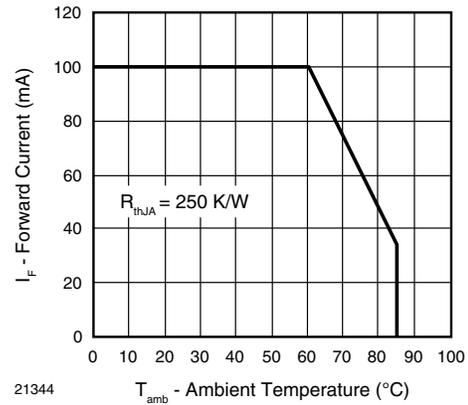


Fig. 2 - Forward Current Limit vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>	1.15	1.35	1.6	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>		2.2		V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>V<sub>F</sub></sub>		- 1.8		mV/K
	I <sub>F</sub> = 100 mA	TK <sub>V<sub>F</sub></sub>		- 1.1		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>			10	μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0 mW/cm <sup>2</sup>	C <sub>J</sub>		70		pF
Radiant intensity	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	I <sub>e</sub>	20	40	60	mW/sr
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	I <sub>e</sub>		330		mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	φ <sub>e</sub>		40		mW
Temperature coefficient of radiant power	I <sub>F</sub> = 1 mA	TK <sub>φ<sub>e</sub></sub>		- 1.1		%/K
	I <sub>F</sub> = 100 mA	TK <sub>φ<sub>e</sub></sub>		- 0.51		%/K
Angle of half intensity		φ		± 12		deg
Peak wavelength	I <sub>F</sub> = 30 mA	λ <sub>p</sub>	920	940	960	nm
Spectral bandwidth	I <sub>F</sub> = 30 mA	Δλ		25		nm
Temperature coefficient of λ <sub>p</sub>	I <sub>F</sub> = 30 mA	TK <sub>λ<sub>p</sub></sub>		0.25		nm/K
Rise time	I <sub>F</sub> = 100 mA, 20 % to 80 %	t <sub>r</sub>		15		ns
Fall time	I <sub>F</sub> = 100 mA, 20 % to 80 %	t <sub>f</sub>		15		ns
Cut-off frequency	I <sub>DC</sub> = 70 mA, I <sub>AC</sub> = 30 mA pp	f <sub>c</sub>		23		MHz
Virtual source diameter		d		1.5		mm

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

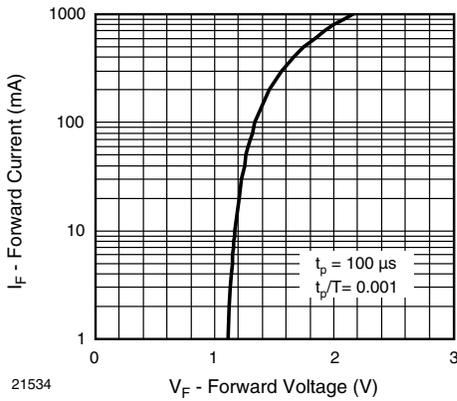


Fig. 3 - Forward Current vs. Forward Voltage

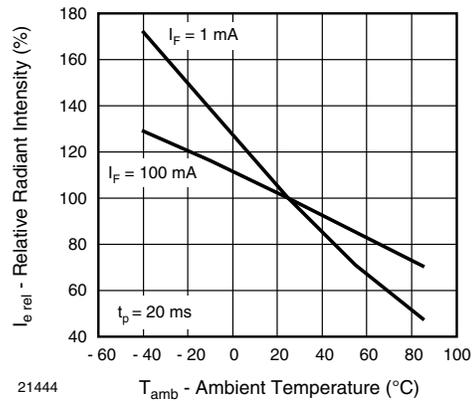


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

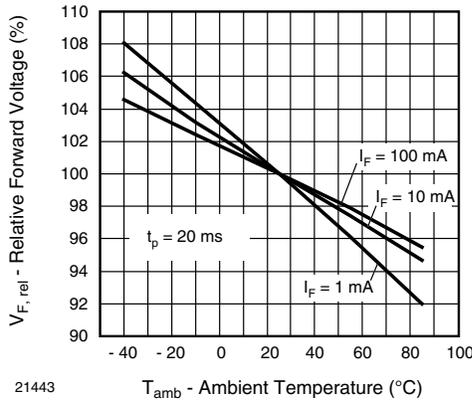


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

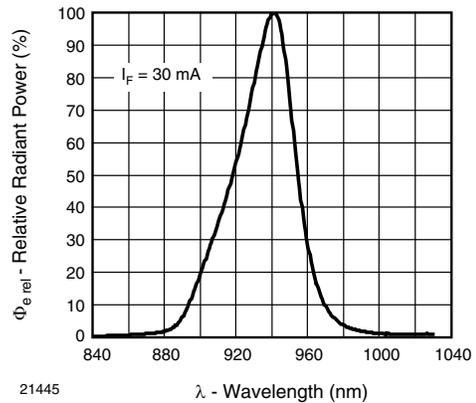


Fig. 7 - Relative Radiant Power vs. Wavelength

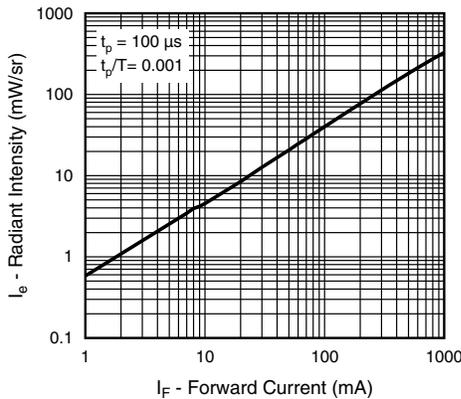


Fig. 5 - Radiant Intensity vs. Forward Current

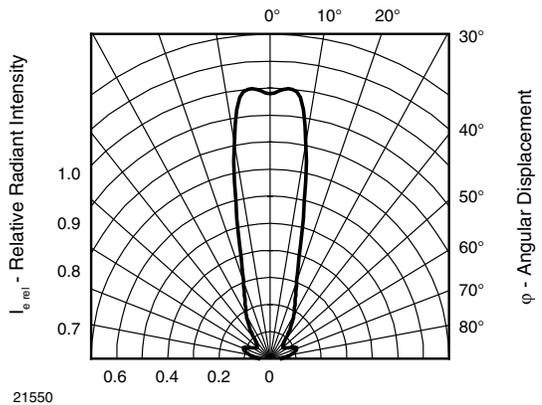


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

## SOLDER PROFILE

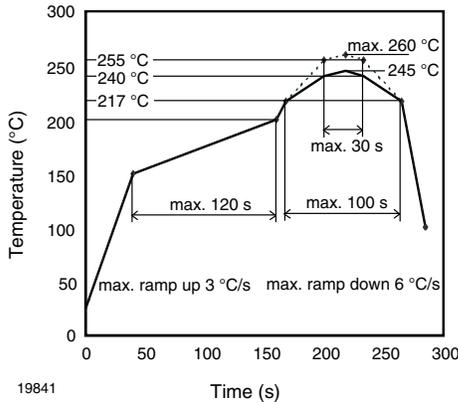


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

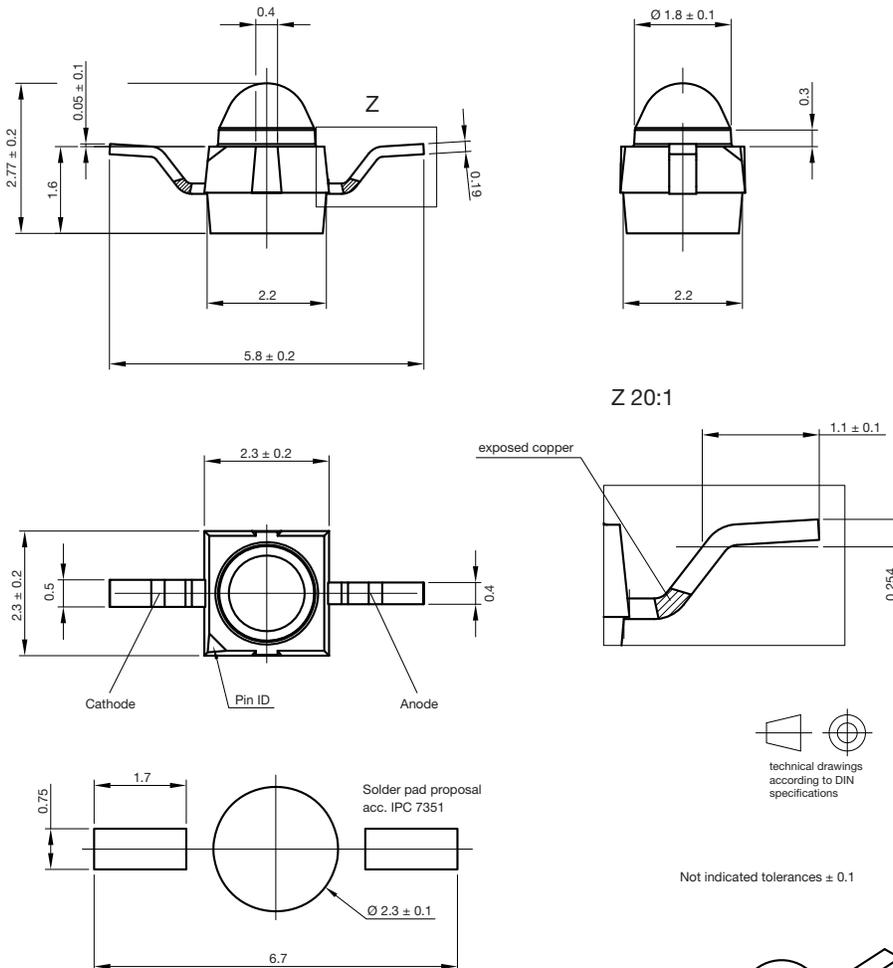
Conditions:  $T_{amb} < 30\text{ °C}$ , RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

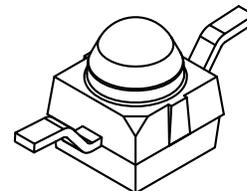
## DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

## PACKAGE DIMENSIONS in millimeters: VSMB2000

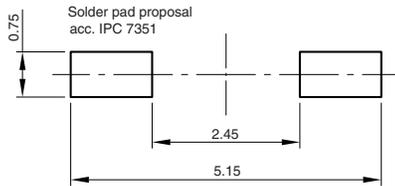
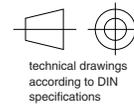
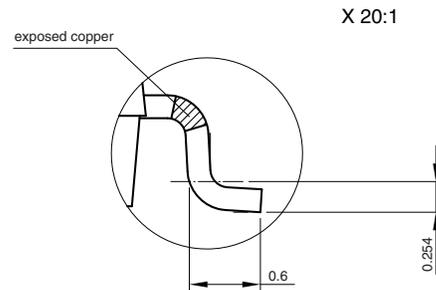
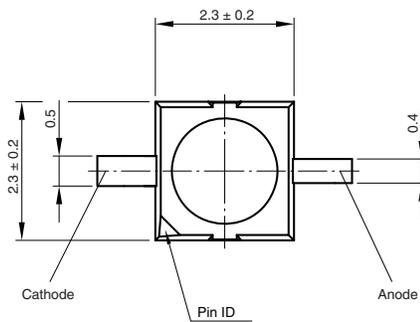
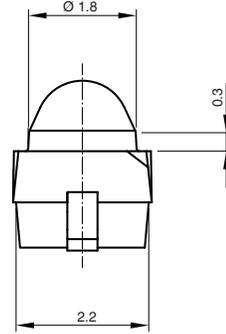
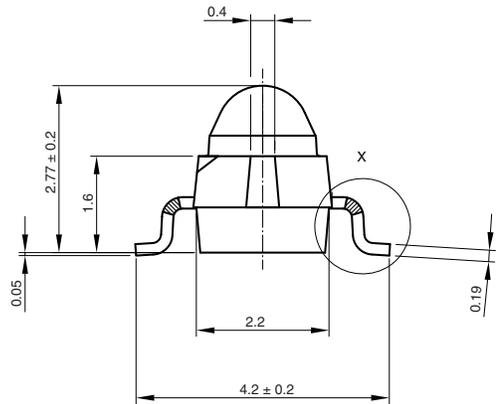


Drawing-No.: 6.544-5391.02-4  
Issue: 2; 18.03.10  
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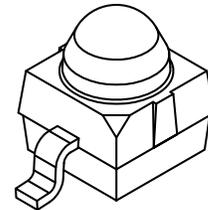




## PACKAGE DIMENSIONS in millimeters: VSMB2020



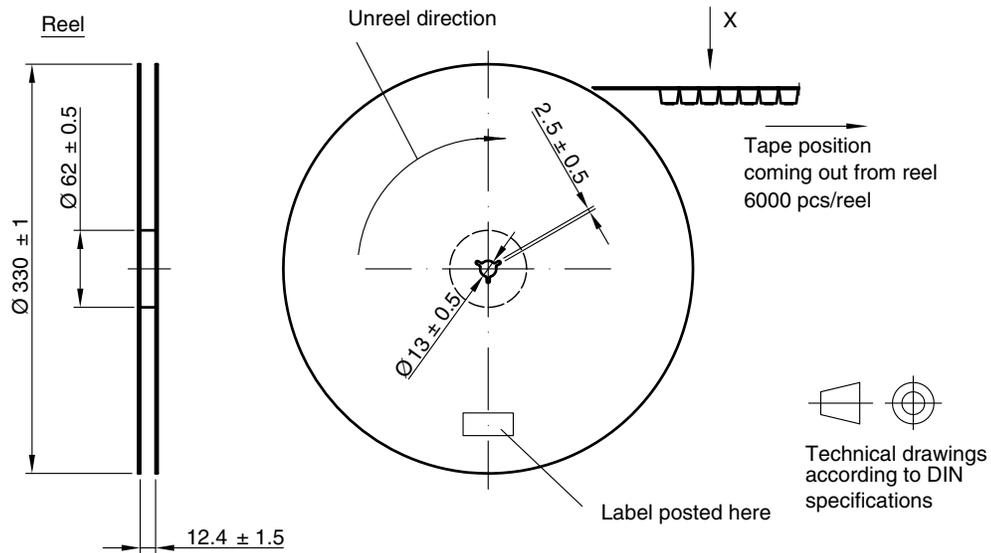
Not indicated tolerances ± 0.1



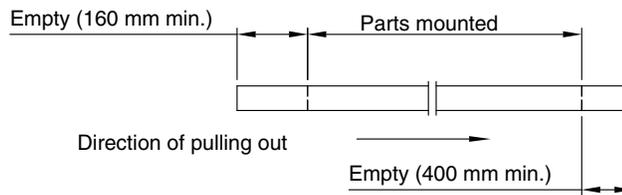
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**TAPING AND REEL DIMENSIONS** in millimeters: **VSMB2000**

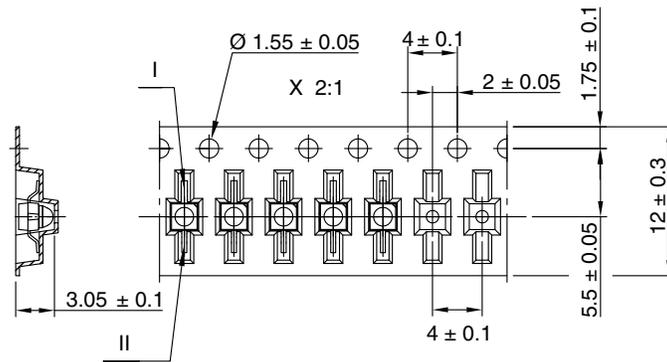


Leader and trailer tape:



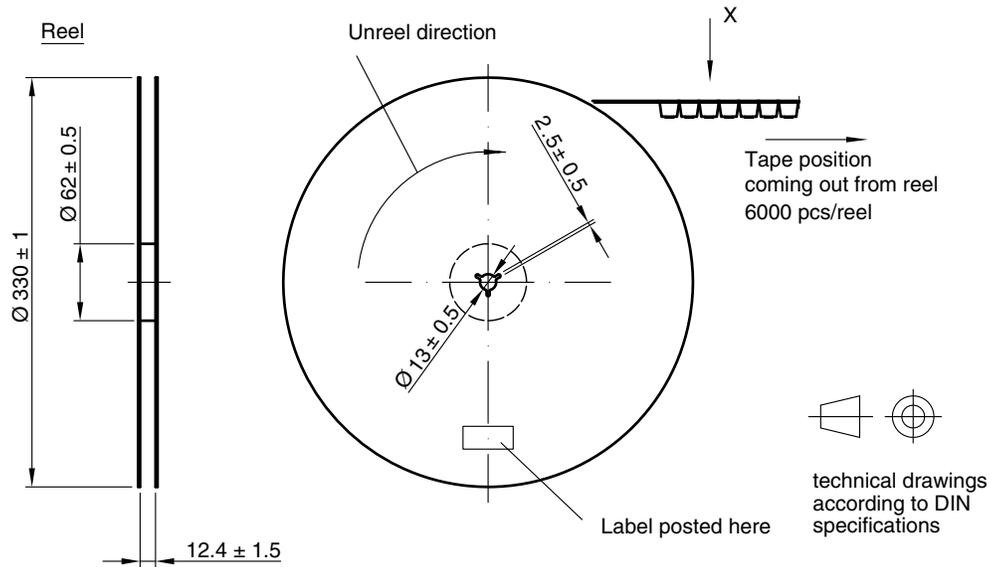
Terminal position in tape

Device	Lead I	Lead II
VENT2000	Collector	Emitter
VENT2500		Emitter
VEMD2000	Cathode	Anode
VEMD2500		
VSMB2000		
VSMG2000	Anode	Cathode
VSMY2850RG		

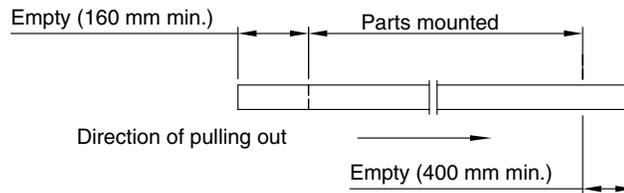


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 Issue: 2; 18.03.10  
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## TAPING AND REEL DIMENSIONS in millimeters: VSMB2020

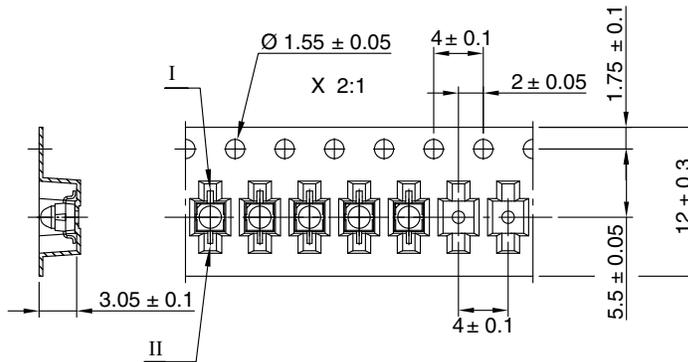


### Leader and trailer tape:



### Terminal position in tape

Device	Lead I	Lead II
VENT2020	Collector	Emitter
VENT2520		Emitter
VSMB2020	Cathode	Anode
VSMG2020		
VEMD2020		
VEMD2520		
VSMY2850G	Anode	Cathode



Drawing-No.: 9.800-5091.01-4

Issue: 3; 18.03.10

21571



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